

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Add device type 05. Add footnote reference <u>1</u> / to table I. Changes on figure 4. Editorial changes throughout.	93-01-13	M. A. FRYE

THE ORIGINAL FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED.

REV	A	A	A	A																
SHEET	35	36	37	38																
REV	A	A	A	A	A		A			A	A	A	A	A	A	A	A	A	A	A
SHEET	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34

REV STATUS OF SHEETS	REV	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A
	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13	14					

PMIC N/A STANDARDIZED MILITARY DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE ANSC N/A	PREPARED BY Kenneth Rice	DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	
	CHECKED BY Charles Reusing		
	APPROVED BY Michael A. Frye	MICROCIRCUITS, MEMORY, DIGITAL, CMOS 2K X 9 PARALLEL-SERIES FIFO, MONOLITHIC SILICON	
	DRAWING APPROVAL DATE 89-11-09		
	REVISION LEVEL A	SIZE A	CAGE CODE 67268

DESC FORM 193

JUL 91

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E586-92

1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:

5962-89942	01	Q	X
Drawing number	Device type (see 1.2.1)	Case outline (see 1.2.2)	Lead finish (see 1.2.3)

1.2.1 Device type(s). The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit function	Access time
01	(see 6.6)	2k X 9-bit parallel-serial FIFO	120 ns
02	(see 6.6)	2k X 9-bit parallel-serial FIFO	80 ns
03	(see 6.6)	2k X 9-bit parallel-serial FIFO	65 ns
04	(see 6.6)	2k X 9-bit parallel-serial FIFO	50 ns
05	(see 6.6)	2k X 9-bit parallel-serial FIFO	40 ns

1.2.2 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
Q	GDIP1-T40 or CDIP2-T40	40	Dual-in-line
X	CQCC1-N44	44	Square leadless chip carrier

1.3 Absolute maximum ratings.

Terminal voltage with respect to ground	-0.5 V dc to +7.0 V dc
DC output current	50 mA
Storage temperature range	-65°C to +150°C
Maximum power dissipation (P_D)	1.0 W
Lead temperature (soldering, 10 seconds)	+260°C
Thermal resistance, junction-to-case (θ_{JC})	See MIL-STD-1835
Junction temperature (T_J)	+150°C 1/

1.4 Recommended operating conditions.

Supply voltage range (V_{CC})	4.5 V dc to 5.5 V dc
Minimum high level input voltage (V_{IH})	2.2 V dc
Maximum low level input voltage (V_{IL})	+0.8 V dc 2/
Case operating temperature range (T_C)	-55°C to +125°C

1/ Maximum junction temperature may be increased to +175°C during burn-in and steady-state life.

2/ 1.5 V undershoots are allowed for 10 ns once per cycle.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 2

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and bulletin. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARDS

MILITARY

MIL-STD-480 - Configuration Control - Engineering Changes, Deviation and Waivers.
MIL-STD-883 - Test Methods and Procedures for Microelectronics.
MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth tables. The truth tables shall be as specified on figure 2.

3.2.3 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
3

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified		Device type	Group A subgroups	Limits		Unit
						Min	Max	
Input leakage current	I _{LI}	0.4 V ≤ V _{IN} ≤ V _{OUT}		ALL	1,2,3	-10	10	μA
Output leakage current	I _{LO}	0.4 V ≤ V _{OUT} ≤ V _{CC} , $\bar{R} \geq V_{IH}$		ALL	1,2,3	-10	10	μA
Output low voltage	V _{OL}	V _{CC} = 4.5 V, V _{IL} = 0.8 V, V _{IH} = 2.2 V	SO, I _{OUT} = 16 mA	ALL	1,2,3		0.4	V
			All other outputs, I _{OUT} = 8.0 mA				0.4	
Output high voltage	V _{OH}	V _{CC} = 4.5 V, V _{IL} = 0.8 V, V _{IH} = 2.2 V	SO, I _{OUT} = -8.0 mA	ALL	1,2,3	2.4		V
			All other outputs, I _{OUT} = -2.0 mA			2.4		
Power supply current	I _{CC1}	f = f _S , outputs open, V _{CC} = 5.5 V		ALL	1,2,3		160	mA
Average standby current	I _{CC2}	$\bar{R} = \bar{W} = \overline{RS} = \overline{FL/RT} = V_{IH}$, outputs open		ALL	1,2,3		25	mA
Power down current	I _{CC3}	$\overline{RS} = \overline{FL/RT} = \bar{W} = \bar{R} =$ V _{CC} - 0.2 V, all other inputs ≥ V _{CC} - 0.2 V or ≤ 0.2 V, outputs open		ALL	1,2,3		4.0	mA
Input capacitance	C _{IN}	V _I = 0 V, f = 1.0 MHz, T _A = +25°C, see 4.3.1c		ALL	4		10	pF
Output capacitance	C _{OUT}	V _O = 0 V, f = 1.0 MHz, T _A = +25°C, see 4.3.1c		ALL	4		12	pF

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET

4

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Parallel I/O shift frequency	f _S	C _L = 30 pF, see figures 3 and 4	01	9,10,11		7.0	MHz
			02			10	
			03			12.5	
			04			15	
			05			20	
Serial-out shift frequency	f _{SOCP}		01	9,10,11		25	MHz
			02			28	
			03			33	
			04			40	
			05			50	
Serial-in shift frequency	f _{SICP}		01	9,10,11		25	MHz
			02			28	
			03			33	
			04			40	
			05			50	

PARALLEL OUTPUT MODE TIMINGS

Access time	t _A	C _L = 30 pF, see figures 3 and 4	01	9,10,11		120	ns
			02			80	
			03			65	
			04			50	
			05			40	

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
5

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Read recovery time	t _{RR}	C _L = 30 pF, see figures 3 and 4	01,02	9,10,11	20		ns
			03,04		15		
			05		10		
Read pulse width	t _{RPW}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Read cycle time	t _{RC}		01	9,10,11	140		ns
			02		100		
			03		80		
			04		65		
			05		50		
Write pulse low to data bus at low Z <u>1</u> /	t _{WLZ}		01,02	9,10,11	20		ns
			03,04		15		
			05		5		
Read pulse low to data bus at low Z <u>1</u> /	t _{RLZ}		01,02,03,04	9,10,11	10		ns
			05		5		
Read pulse high to data bus at high Z <u>1</u> /	t _{RHZ}		01,02	9,10,11		35	ns
			03,04			30	
			05			25	
Data valid from read pulse high	t _{DV}		All	9,10,11	5.0		ns

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET

6

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
PARALLEL INPUT MODE TIMINGS							
Data setup time	t _{DS}	C _L = 30 pF, see figures 3 and 4	01,02	9,10,11	40		ns
			03,04		30		
			05		20		
Data hold time	t _{DH}		01,02, 03	9,10,11	10		ns
			04		5.0		
			05		0		
Write cycle time	t _{WC}		01	9,10,11	140		ns
			02		100		
			03		80		
			04		65		
			05		50		
Write pulse width	t _{WPW}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Write recovery time	t _{WR}		01,02	9,10,11	20		ns
			03,04		15		
			05		10		

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
7

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
RESET TIMINGS							
Reset cycle time	t _{RSC}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	140		ns
			02		100		
			03		80		
			04		65		
			05		50		
Reset pulse width	t _{RS}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Reset setup time <u>1</u> /	t _{RSS}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Reset recovery time	t _{RSR}		01,02	9,10,11	20		ns
			03,04		15		
			05		10		

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
8

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
RESET TO FLAGS DELAYS							
Reset to $\overline{\text{EF}}$, $\overline{\text{AEF}}$, and $\overline{\text{EF}+1}$ low	t _{RSF1}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			50	
Reset to $\overline{\text{HF}}$, $\overline{\text{FF}}$, and $\overline{\text{FF}-1}$ high	t _{RSF2}		01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			50	
RESET TO TIME DELAYED OUTPUTS - SERIAL MODE ONLY							
Reset going low to Q ₀₋₈ low	t _{RSQL}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	105		ns
			02		65		
			03		50		
			04		35		
			05		20		
Reset going high to Q ₀₋₈ high	t _{RSQH}		01	9,10,11	105		ns
			02		65		
			03		50		
			04		35		
			05		20		

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
9

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$ $V_{SS} = 0\text{ V}, 4.5\text{ V} \leq V_{CC} < 5.5\text{ V}$ unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Reset going low to D_{0-8} low	t_{RSDL}	$C_L = 30\text{ pF}$, see figures 3 and 4	01	9,10,11	105		ns
			02		65		
			03		50		
			04		35		
			05		20		

RETRANSMIT TIMINGS

Retransmit cycle time	t_{RTC}	$C_L = 30\text{ pF}$, see figures 3 and 4	01	9,10,11	140		ns
			02		100		
			03		80		
			04		65		
			05		50		
Retransmit pulse width	t_{RT}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Retransmit setup time $1/$	t_{RTS}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 10

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_c \leq +125^{\circ}\text{C}$ $V_{SS} = 0\text{ V}, 4.5\text{ V} \leq V_{CC} < 5.5\text{ V}$ unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Retransmit recovery time	t_{RTR}	$C_L = 30\text{ pF}$, see figures 3 and 4	01,02	9,10,11	20		ns
			03,04		15		
			05		10		

PARALLEL MODE FLAG PROPAGATION DELAYS

Read low to $\overline{\text{EF}}$ low	t_{REF}	$C_L = 30\text{ pF}$, see figures 3 and 4	01,02, 03	9,10,11		60	ns
			04			45	
			05			35	
Read high to $\overline{\text{FF}}$ high	t_{RFF}		01,02 03	9,10,11		60	ns
			04			45	
			05			35	
Read high to <u>transitioning</u> HF, AEF, and FF-1	t_{RF}		01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			50	
Read low to <u>transitioning</u> AEF and EF+1	t_{RE}		01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			45	

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET

11

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Read pulse width after EF high	t _{RPE}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Write high to EF high	t _{WEF}		01,02, 03	9,10,11		60	ns
			04			45	
			05			35	
Write low to FF low	t _{WFF}		01,02, 03	9,10,11		60	ns
			04			45	
			05			35	
Write low to transitioning HF, AEF, and FF-1	t _{WF}		01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
		05			50		
Write high to transitioning AEF and EF+1	t _{WE}	01	9,10,11		140	ns	
		02			100		
		03			80		
		04			65		
		05			50		

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET

12

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$ $V_{SS} = 0\text{ V}, 4.5\text{ V} \leq V_{CC} < 5.5\text{ V}$ unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Write pulse width after $\overline{\text{FF}}$ high	t_{WPF}	$C_L = 30\text{ pF}$, see figures 3 and 4	01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		

DEPTH EXPANSION MODE DELAYS

Read/write to $\overline{\text{X0}}$ low	t_{XOL}	$C_L = 30\text{ pF}$, see figures 3 and 4	01	9,10,11		120	ns
			02			80	
			03			65	
			04			50	
			05			40	
Read/write to $\overline{\text{X0}}$ high	t_{XOH}		01	9,10,11		120	ns
			02			80	
			03			65	
			04			50	
			05			40	
$\overline{\text{XI}}$ pulse width	t_{XI}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET

13

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
$\overline{\text{XI}}$ recovery time	t _{XIR}	C _L = 30 pF, see figures 3 and 4	ALL	9,10,11	10		ns
$\overline{\text{XI}}$ setup time	t _{XIS}		ALL	9,10,11	15		ns

SERIAL INPUT MODE TIMINGS

Serial data in setup time to SICP rising edge	t _{s2}	C _L = 30 pF, see figures 3 and 4	01,02	9,10,11	20		ns
			03,04		15		
			05		12		
Serial data in hold time to SICP rising edge	t _{H2}		01,02	9,10,11	5.0		ns
			03,04, 05		0		
SIX setup time to SICP rising edge	t _{s3}		ALL	9,10,11	5.0		ns
$\overline{\text{W}}$ setup time to SICP rising edge	t _{s4}		ALL	9,10,11	5.0		ns
$\overline{\text{W}}$ hold time to SICP rising edge	t _{H4}		01	9,10,11	15		ns
			02		12		
			03		10		
			04,05		7.0		
Serial in clock width high/low	t _{SICW}		01,02	9,10,11	15		ns
			03,04		10		
			05		8		

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
14

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
$\overline{\text{SI}}$ /PI setup time to SICP rising edge	t _{S5}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		

SERIAL OUTPUT MODE TIMINGS

SO/PO setup time to SOCP rising edge	t _{S6}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
SOX setup time to SOCP rising edge	t _{S7}		ALL	9,10,11	5.0		ns
$\overline{\text{R}}$ setup time to SOCP rising edge	t _{S8}		ALL	9,10,11	5.0		ns
$\overline{\text{R}}$ hold time to SOCP rising edge	t _{H8}		01	9,10,11	15		ns
			02		12		
			03		10		
			04,05		7.0		

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
15

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$ $V_{SS} = 0\text{ V}, 4.5\text{ V} \leq V_{CC} < 5.5\text{ V}$ unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Serial in clock width high/low	t_{SOCW}	$C_L = 30\text{ pF}$, see figures 3 and 4	01,02	9,10,11	15		ns
			03,04		10		
			05		8		

SERIAL MODE RECOVERY TIMINGS

Recovery time SOCP after EF goes high	t_{REFSO}	$C_L = 30\text{ pF}$, see figures 3 and 4	01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Recovery time SICP after FF goes high	t_{REFSI}		01,02	9,10,11	20		ns
			03,04, 05		15		

SERIAL MODE FLAG PROPAGATION DELAYS

SOCP rising edge (bit 0 - first word) to EF low	t_{SOCEF}	$C_L = 30\text{ pF}$, see figures 3 and 4	01,02, 03	9,10,11		30	ns
			04,05			25	
SOCP rising edge (bit 0 - first word) to FF high	t_{SOCFF}		01,02	9,10,11		60	ns
			03			50	
			04			40	
			05			35	

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
16

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$ $V_{SS} = 0\text{ V}, 4.5\text{ V} \leq V_{CC} < 5.5\text{ V}$ unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
SOCP rising edge (bit 0 - second word) to FF-1, HF, AEF, EF+1 high	t_{SOCP}	$C_L = 30\text{ pF}$, see figures 3 and 4	01,02	9,10,11		60	ns
			03			50	
			04			40	
			05			35	
SICP rising edge (bit 0 - first word) to EF high	t_{SICEF}		01,02, 03	9,10,11		80	ns
			04			65	
			05			50	
SICP rising edge (bit 0 - first word) to FF low	t_{SICFF}		01,02	9,10,11		60	ns
			03			50	
			04			40	
			05			35	
SICP rising edge (bit 0 - second word) to EF+1, HF, AEF, FF-1 high	t_{SICF}		01,02, 03	9,10,11		80	ns
			04			65	
			05			50	

SERIAL INPUT MODE DELAYS

SICP rising edge to D 1/	t_{PD1}	$C_L = 30\text{ pF}$, see figures 3 and 4	01	9,10,11	5.0	35	ns
			02		5.0	30	
			03		5.0	25	
			04		5.0	20	
			05		5.0	17	

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET

17

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
SERIAL OUTPUT MODE DELAYS							
SOCP rising edge to Q <u>1</u> /	t _{PD2}	C _L = 30 pF, see figures 3 and 4	01,02	9,10,11	5.0	30	ns
			03		5.0	25	
			04		5.0	20	
			05		5.0	17	
SOCP rising edge to SO at high-Z <u>1</u> /	t _{SOHZ}		01	9,10,11	5.0	30	ns
			02		5.0	25	
			03		5.0	20	
			04,05		5.0	16	
SOCP rising edge to SO at low-Z <u>1</u> /	t _{SOLZ}		01	9,10,11	5.0	35	ns
			02		5.0	30	
			03,04, 05		5.0	22	
SOCP rising edge to valid data on SO	t _{SOPD}		01	9,10,11		35	ns
			02			30	
			03			22	
			04,05			18	

See footnotes at end of table.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET

18

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
OUTPUT ENABLE/DISABLE DELAYS							
Output enable to high-Z (disable) <u>1/</u>	t _{OEZ}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		30	ns
			02			25	
			03			20	
			04,05			16	
Output enable to low-Z (enable) <u>1/</u>	t _{OELZ}		ALL	9,10,11	5.0		ns
Output enable to data valid (Q ₀₋₈)	t _{AOE}		01	9,10,11		35	ns
			02			30	
			03			25	
			04			22	
			05			20	

1/ If not tested, shall be guaranteed to the limits specified in table I.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
19

Device types	All	
Case outlines	Q	X
Terminal number	Terminal symbol	
1	<u>SO</u>	<u>W</u>
2	<u>AEF</u>	D ₄
3	<u>FF-1</u>	D ₃
4	<u>FF</u>	D ₂
5	Q ₀	D ₁
6	Q ₁	GND
7	Q ₂	D ₀
8	Q ₃	<u>XI</u>
9	Q ₄	SO/PO
10	GND	SOX
11	R	SOC P
12	Q ₅	<u>SO</u>
13	Q ₆	<u>AEF</u>
14	Q ₇	<u>FF-1</u>
15	Q ₈	<u>FF</u>
16	<u>XO/HF</u>	Q ₀
17	<u>EF</u>	GND
18	<u>EF+1</u>	Q ₁
19	<u>OE</u>	Q ₂
20	SI/PI	Q ₃
21	SIX	Q ₄
22	SIC P	GND
23	<u>SI</u>	R
24	<u>RS</u>	Q ₅
25	<u>FL/RT</u>	Q ₆
26	D ₈	Q ₇
27	D ₇	Q ₈
28	D ₆	GND
29	D ₅	<u>XO/HF</u>
30	V _{CC}	<u>EF</u>
31	W	<u>EF+1</u>
32	D ₄	<u>OE</u>
33	D ₃	SI/PI
34	D ₂	SIX
35	D ₁	SIC P
36	D ₀	SI
37	<u>XI</u>	<u>RS</u>
38	SO/PO	<u>FL/RT</u>
39	SOX	GND
40	SOC P	D ₈
41	---	D ₇
42	---	D ₆
43	---	D ₅
44	---	V _{CC}

FIGURE 1. Terminal connections.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL	SHEET 20

Reset and retransmit
Single device configuration/width expansion mode

Mode	Inputs			Internal status		Outputs		
	$\overline{\text{RS}}$	$\overline{\text{FL}}$	$\overline{\text{XI}}$	Read pointer	Write pointer	$\overline{\text{AEF}}$, $\overline{\text{EF}}$, $\overline{\text{EF}}+1$	$\overline{\text{FF}}$, $\overline{\text{FF}}-1$	$\overline{\text{HF}}$
Reset	0	X	0	Location zero	Location zero	0	1	1
Retransmit	1	0	0	Location zero	Unchanged	X	X	X
Read/Write	1	1	0	Increment see note 1	Increment see note 1	X	X	X

Reset and first load
Depth expansion/compound expansion mode

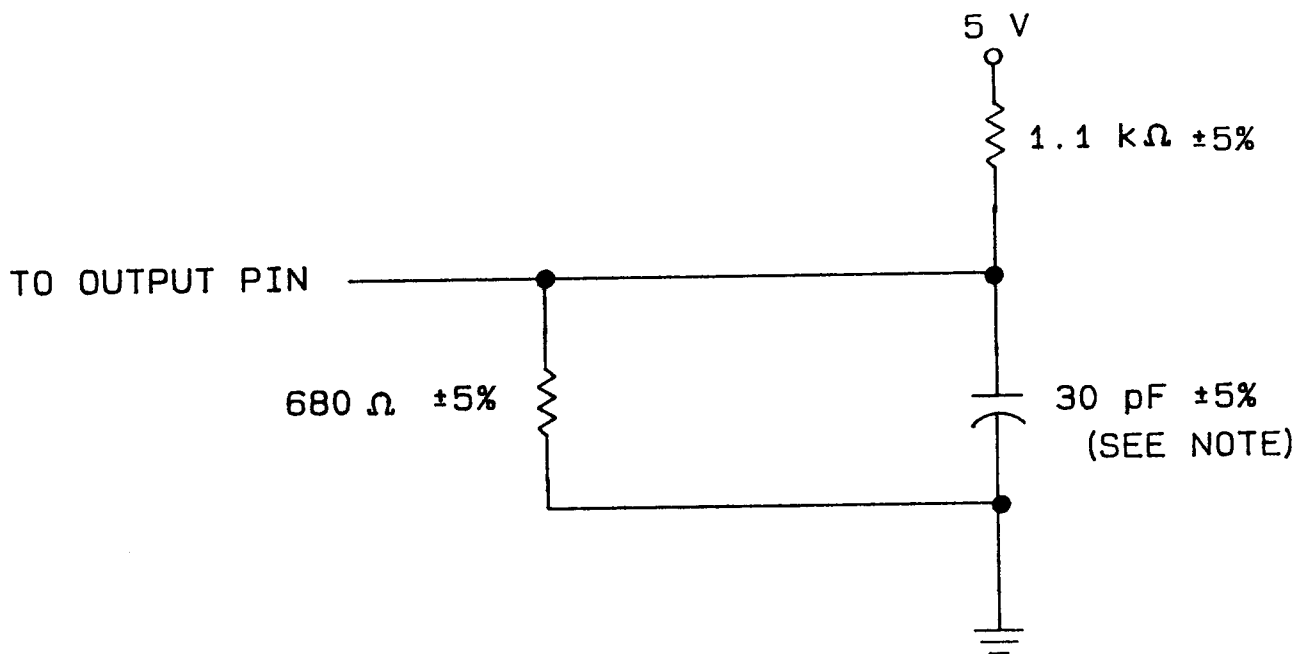
Mode	Inputs			Internal status		Outputs	
	$\overline{\text{RS}}$	$\overline{\text{FL}}$	$\overline{\text{XI}}$	Read pointer	Write pointer	$\overline{\text{EF}}$	$\overline{\text{FF}}$
Reset first device	0	0	See note 2	Location zero	Location zero	0	1
Reset all other devices	0	1	See note 2	Location zero	Location zero	0	1
Read/Write	1	X	See note 2	X	X	X	X

NOTES:

- Pointer will increment if flag is high.
- $\overline{\text{XI}}$ is connected to XO of previous device.
- $\overline{\text{RS}}$ = Reset input, $\overline{\text{FL}}/\overline{\text{RT}}$ = First load/retransmit,
 $\overline{\text{EF}}$ = Empty flag output, $\overline{\text{FF}}$ = Full flag output, $\overline{\text{XI}}$ = Expansion input, and $\overline{\text{HF}}$ = Half-full flag output
 0 = Low level voltage
 1 = High level voltage
 X = Don't care

FIGURE 2. Truth tables.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 21



NOTE: C_L includes scope and jig capacitance.

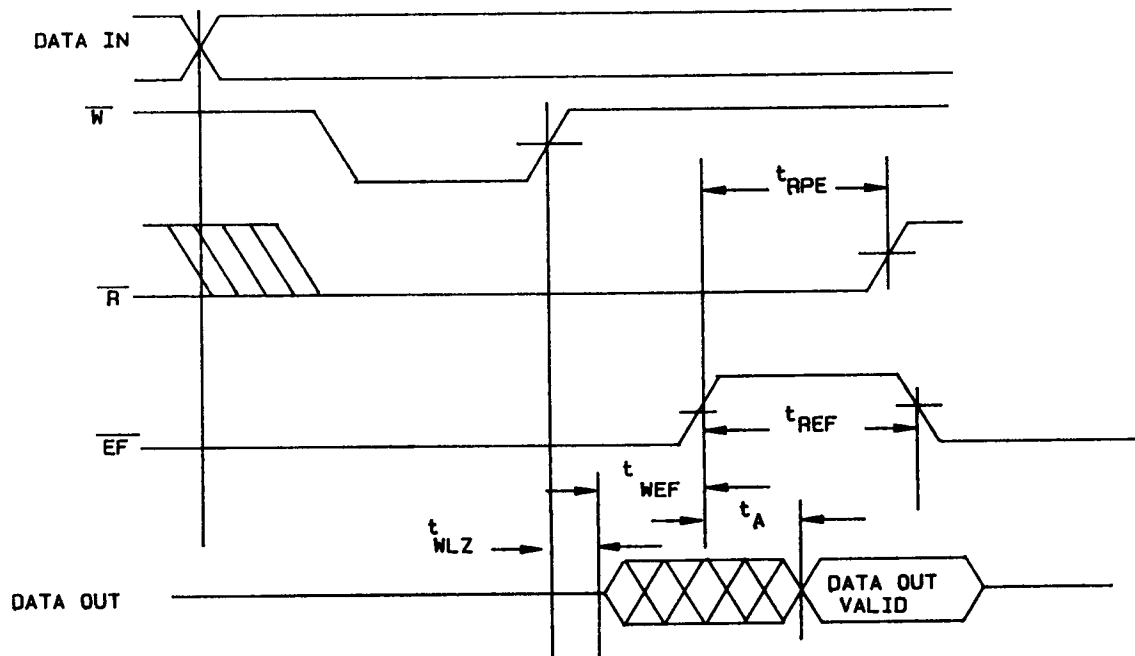
AC test conditions

Input pulse levels	GND to 3.0 V
Input rise and fall times	3.0 ns
Input timing reference levels	1.5 V
Output reference levels	1.5 V

FIGURE 3. Output load circuit and ac test conditions.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL	SHEET 22

FIFO empty boundary condition timing



FIFO full boundary condition timing

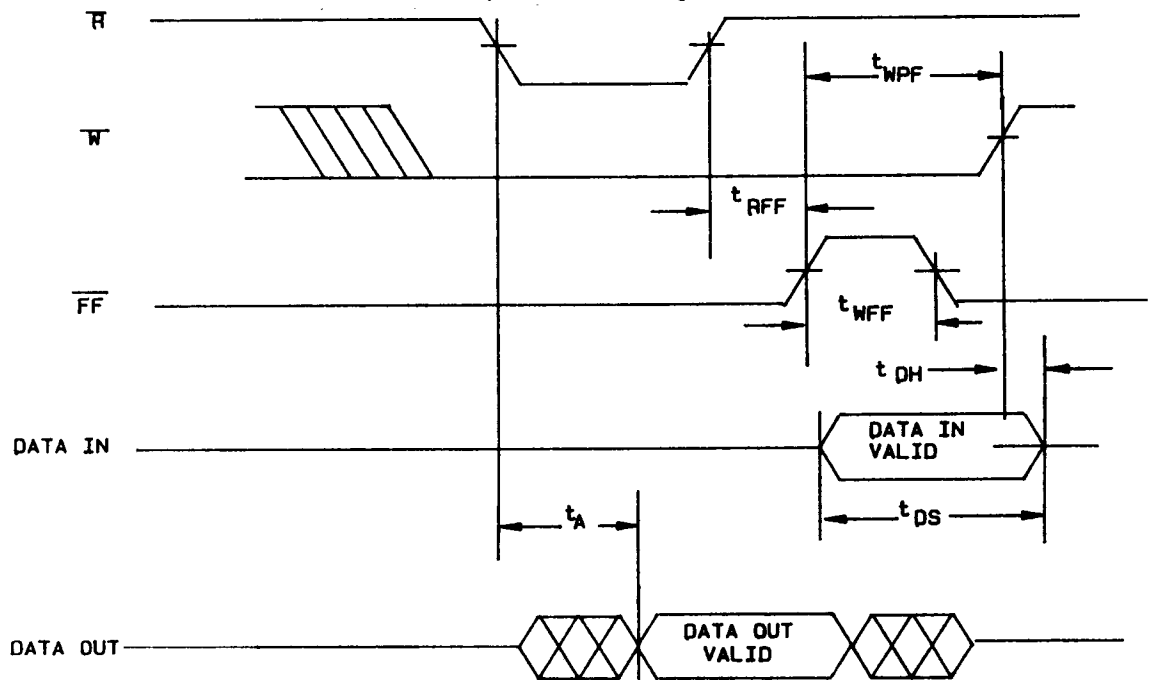


FIGURE 4. Timing waveforms.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

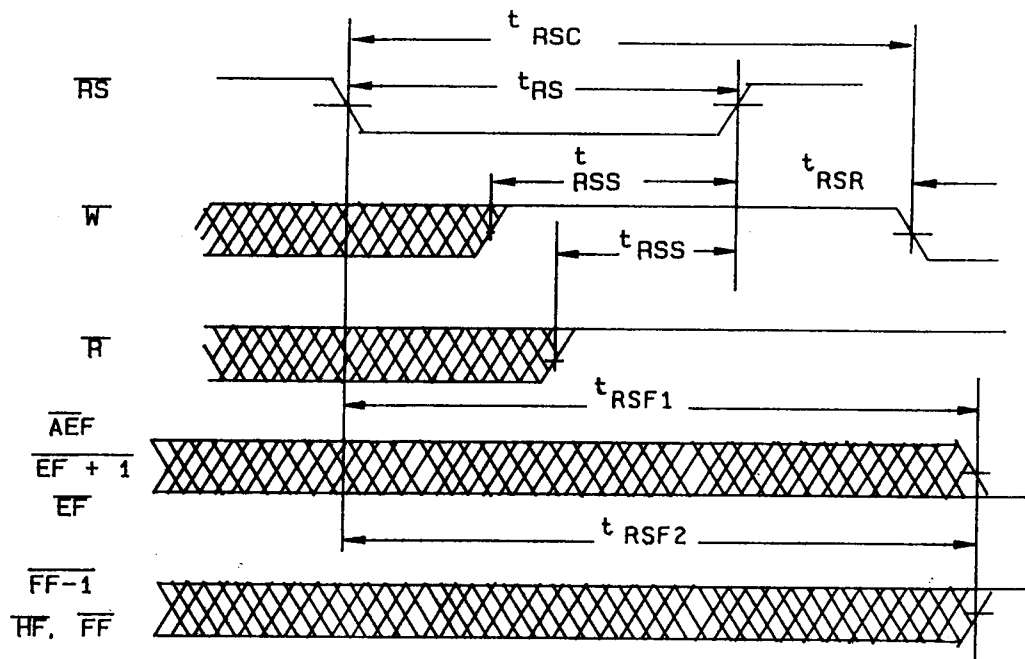
5962-89942

REVISION LEVEL

SHEET

23

Reset timing (see note 1)



Retransmit timing (see note 2)

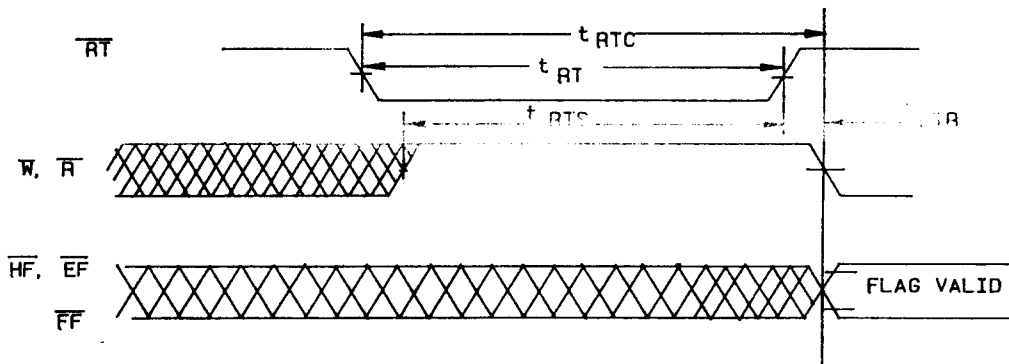
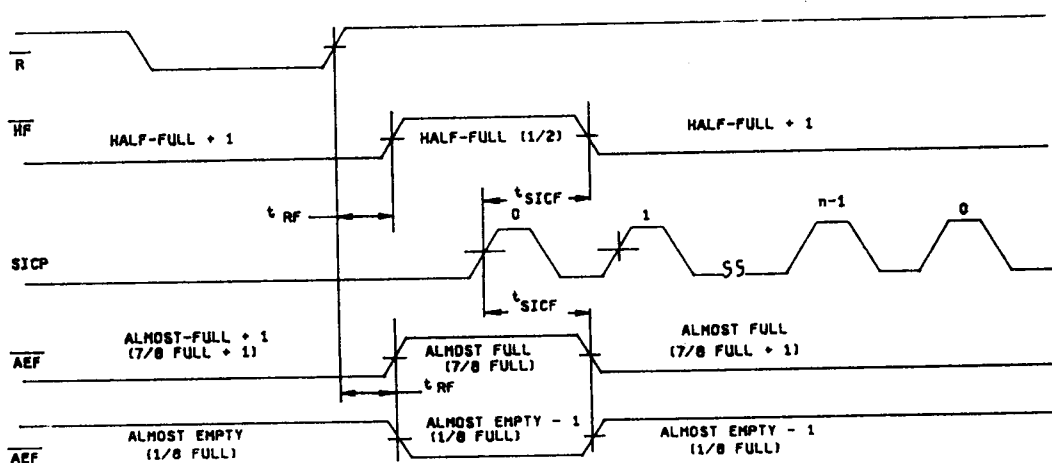


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 24

Half-full, almost-full, and almost-empty timings for serial-in-mode



Half-full, almost-full, and almost-empty timings for serial-out-mode

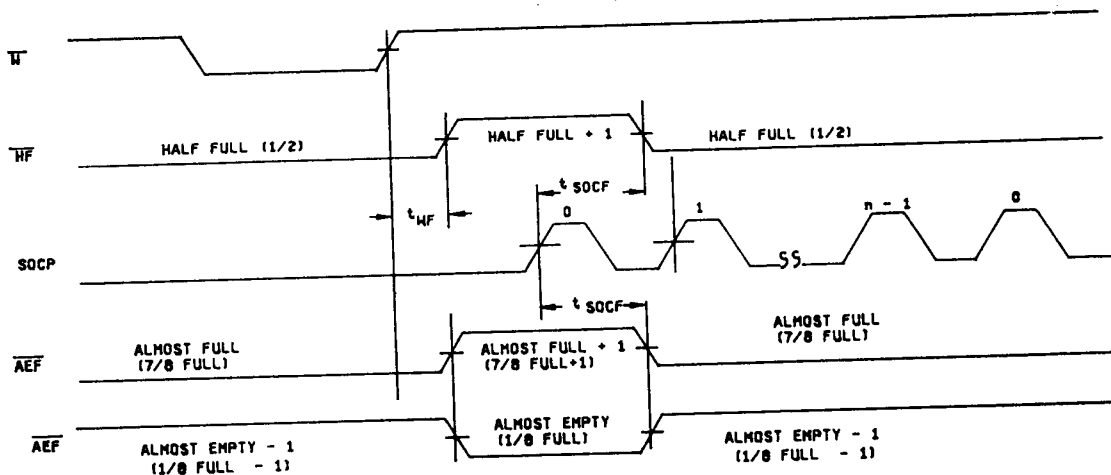


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

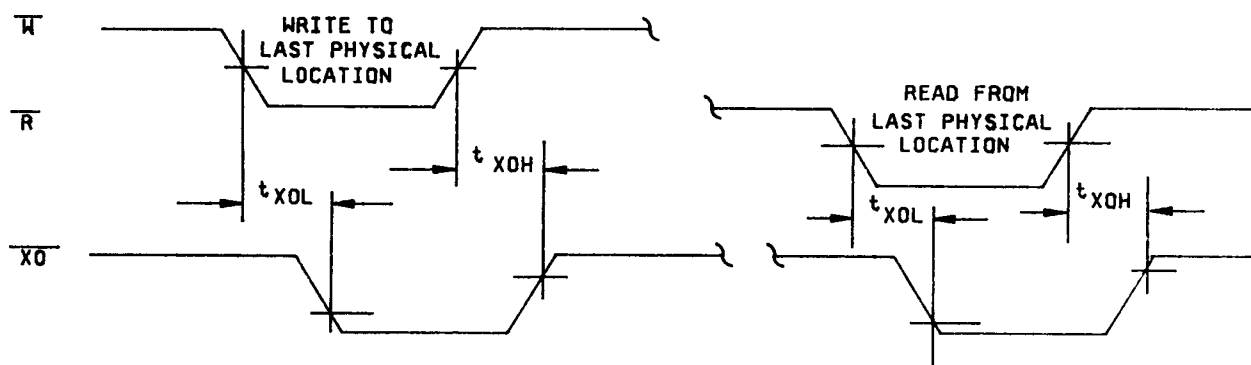
SIZE
A

5962-89942

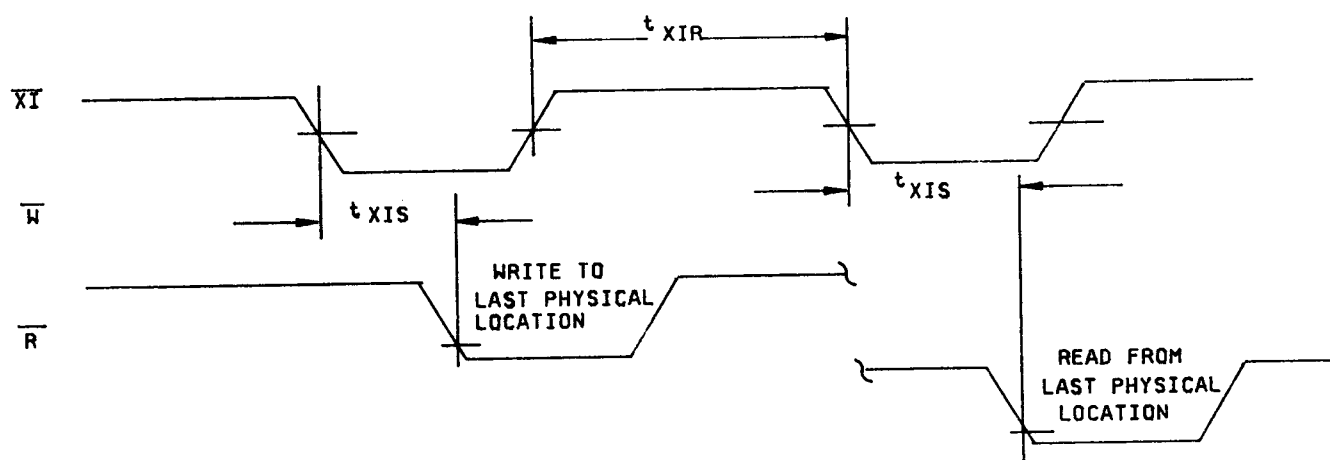
REVISION LEVEL
A

SHEET
25

Expansion out timing



Expansion in timing



Output enable timing

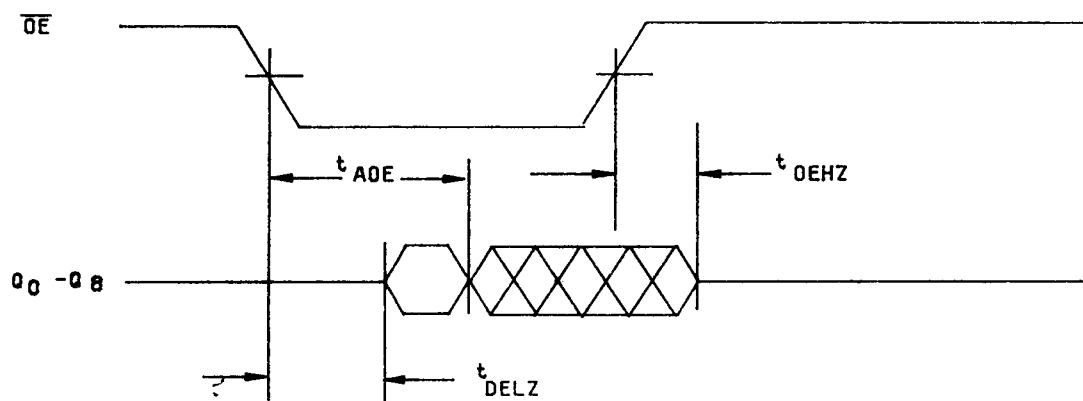


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
26

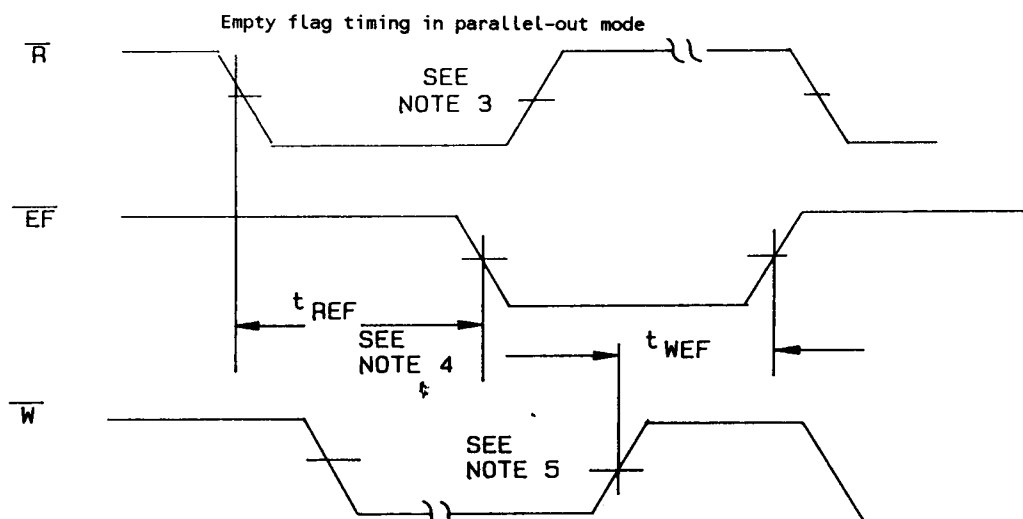
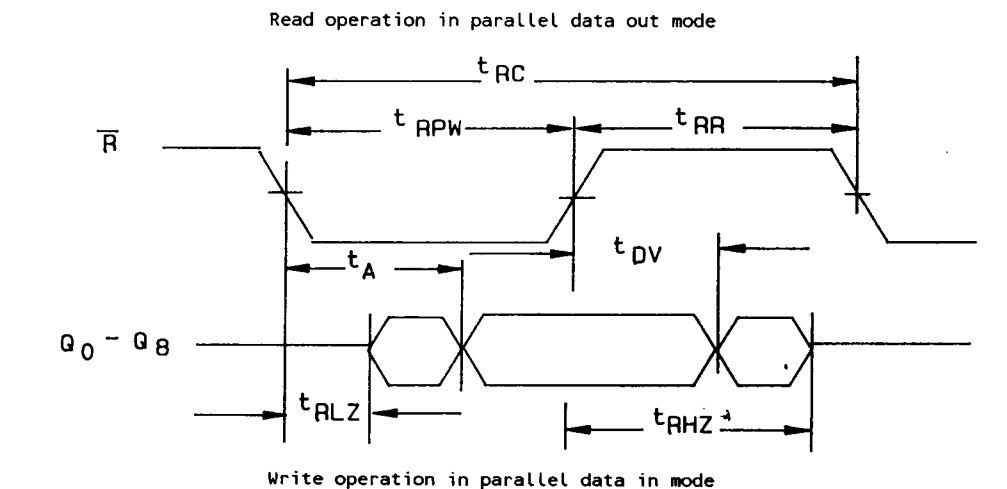


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

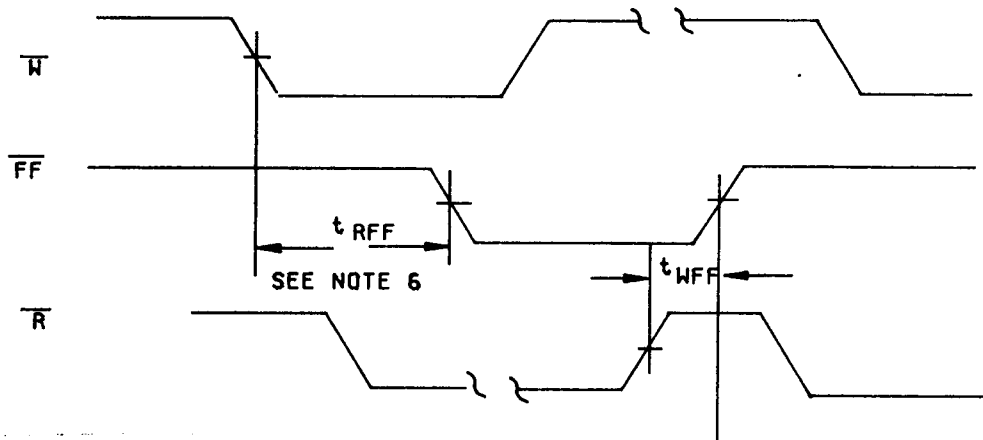
5962-89942

REVISION LEVEL
A

SHEET

27

Full flag timing in parallel-in mode



Almost full, half full, and full - 1 flag timings

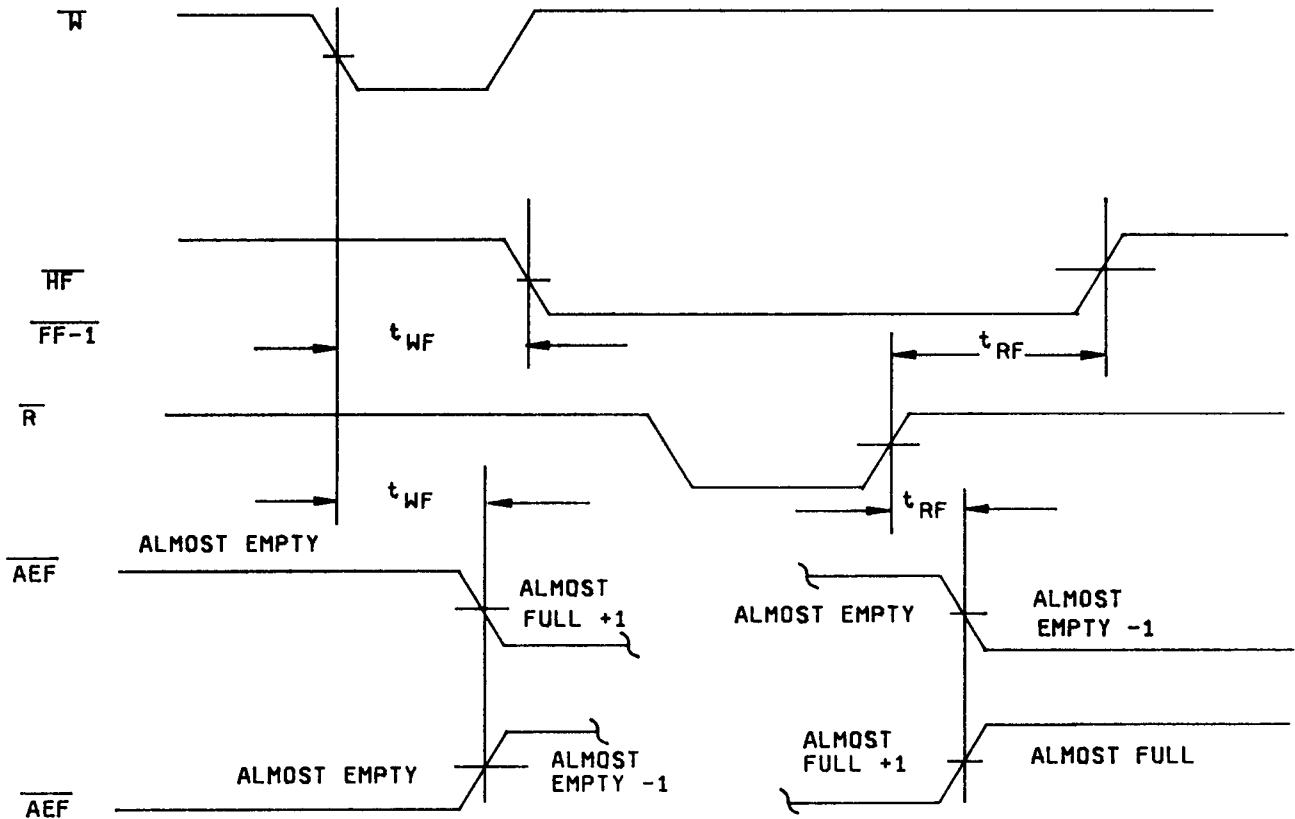


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
28

Empty + 1 flag timings

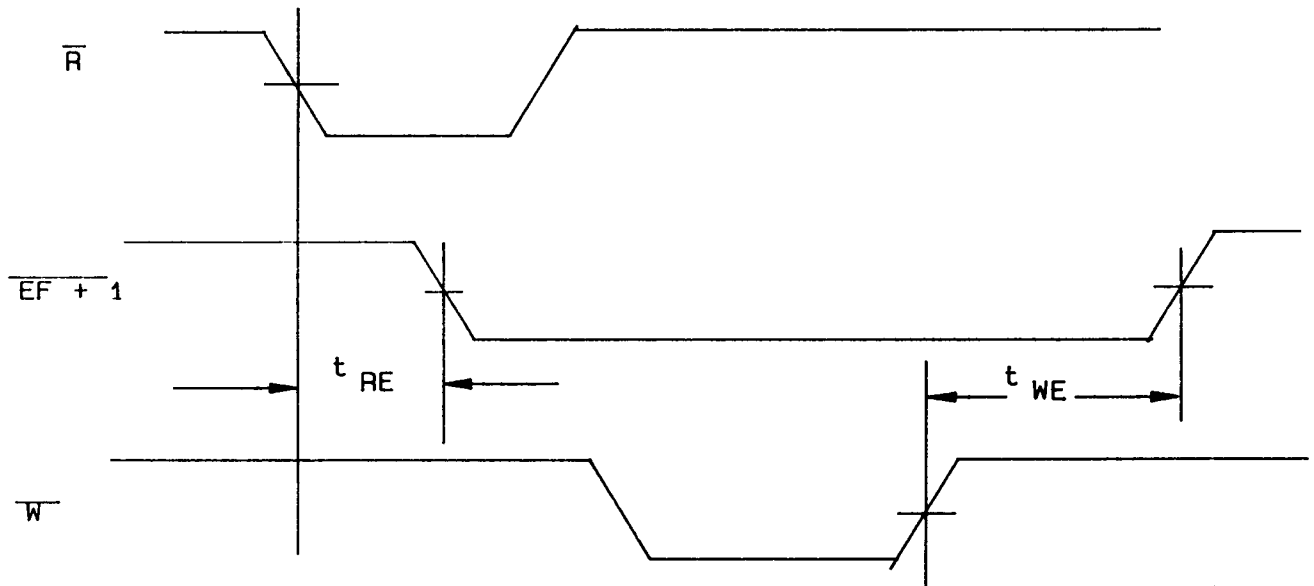


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 29

Read operation in serial-out mode

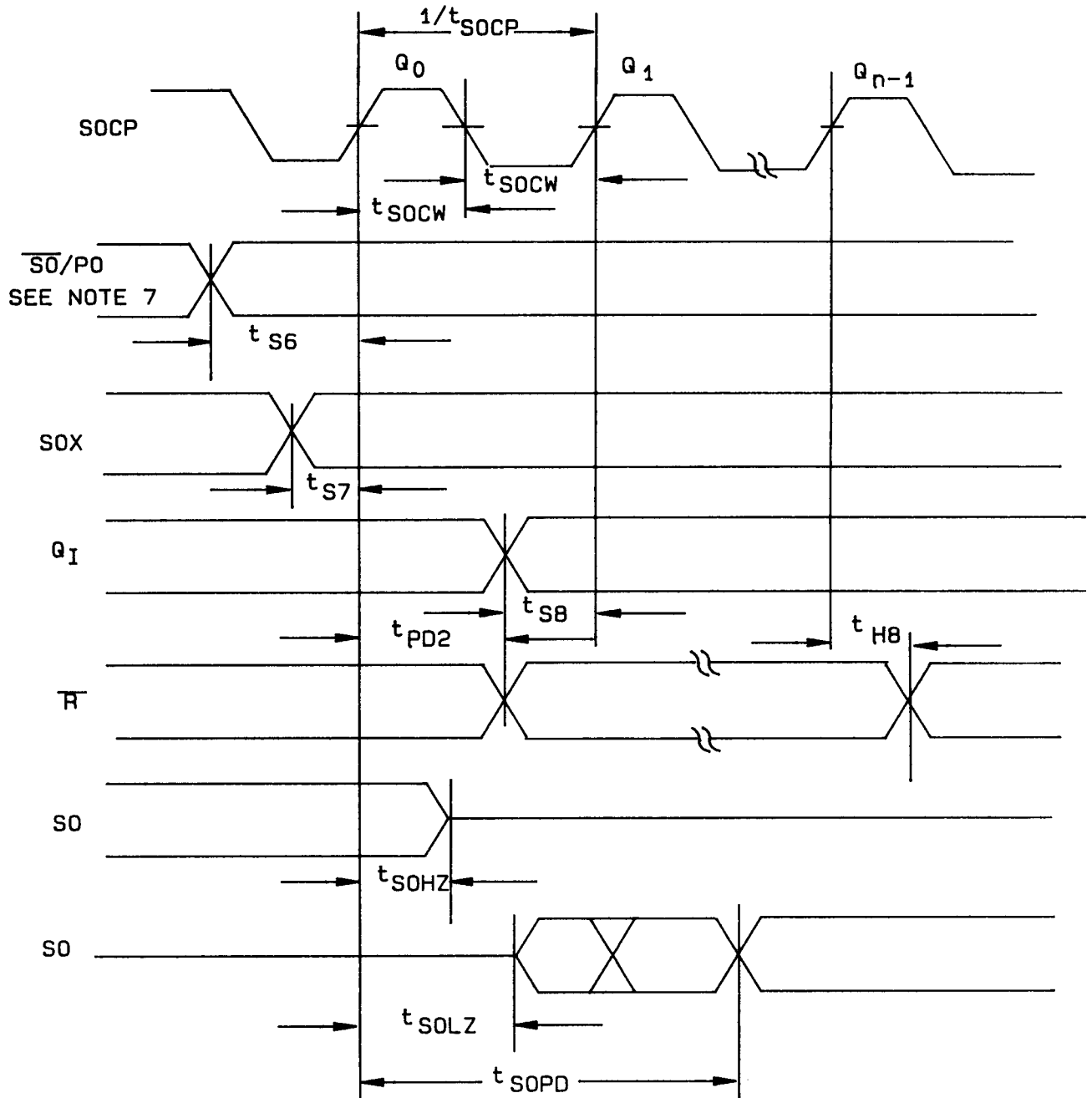


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET

30

Write operation in serial-in mode

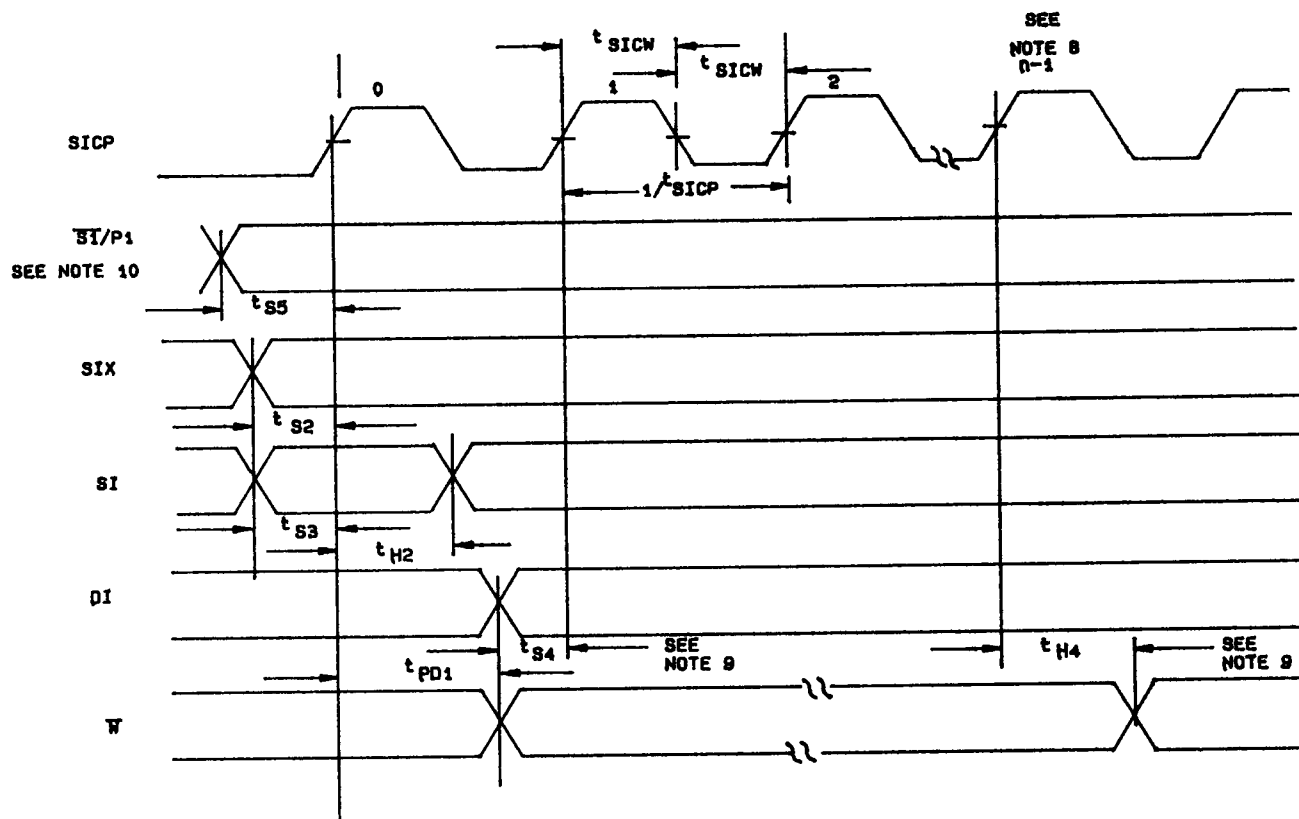


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 31

Full flag and full - 1 flag deassertion in the serial-out mode

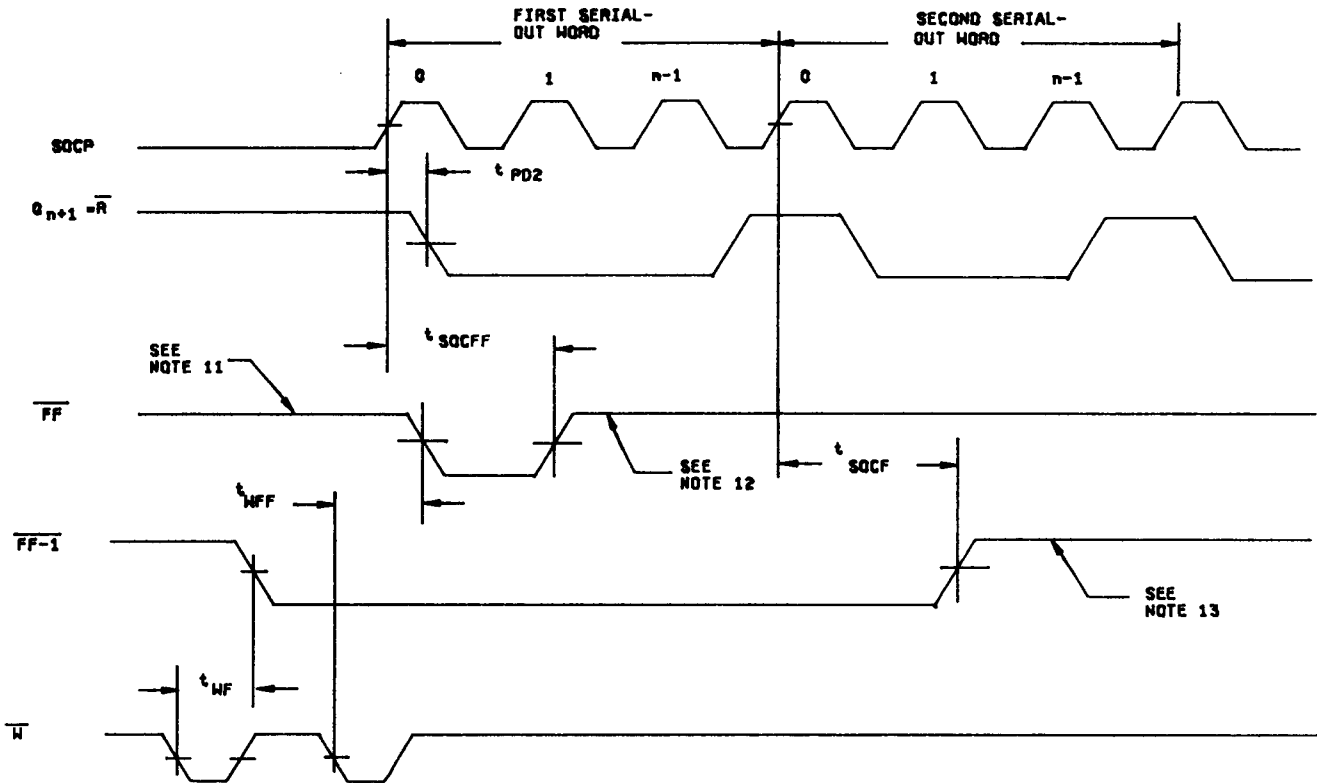


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
32

Empty flag and empty + 1 flag assertion in the serial-out mode,
FIFO being emptied

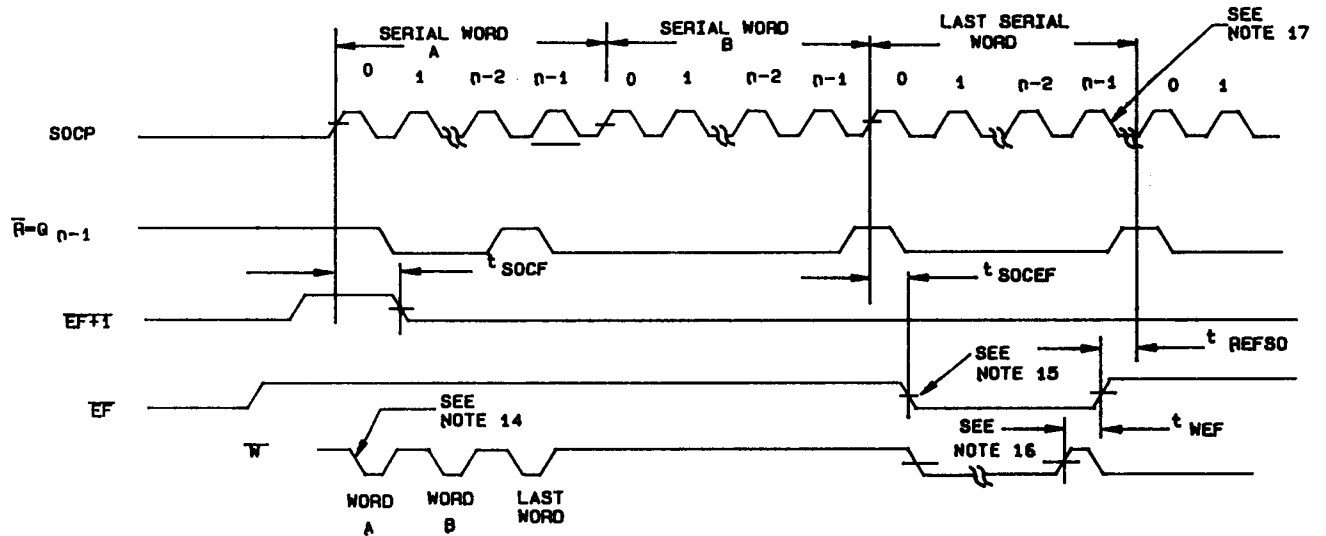


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 33

Full flag and full - 1 flag assertion in the serial-in mode,
FIFO being filled

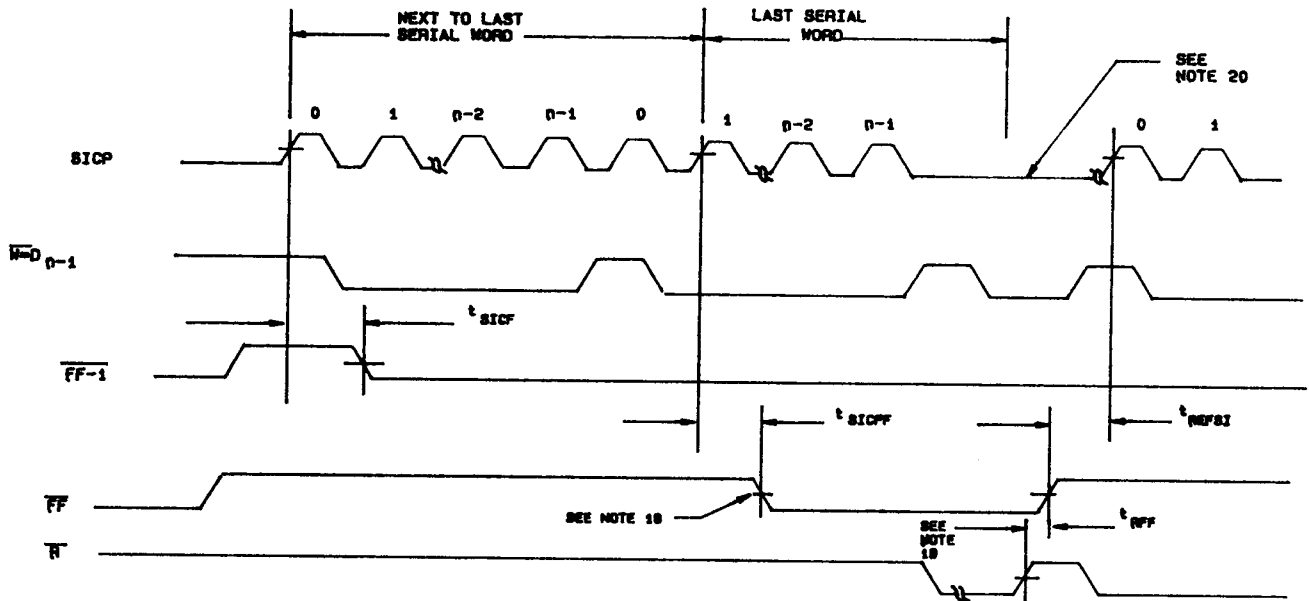


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-89942

REVISION LEVEL
A

SHEET
34

Empty flag and empty + 1 flag deassertion in serial-in mode

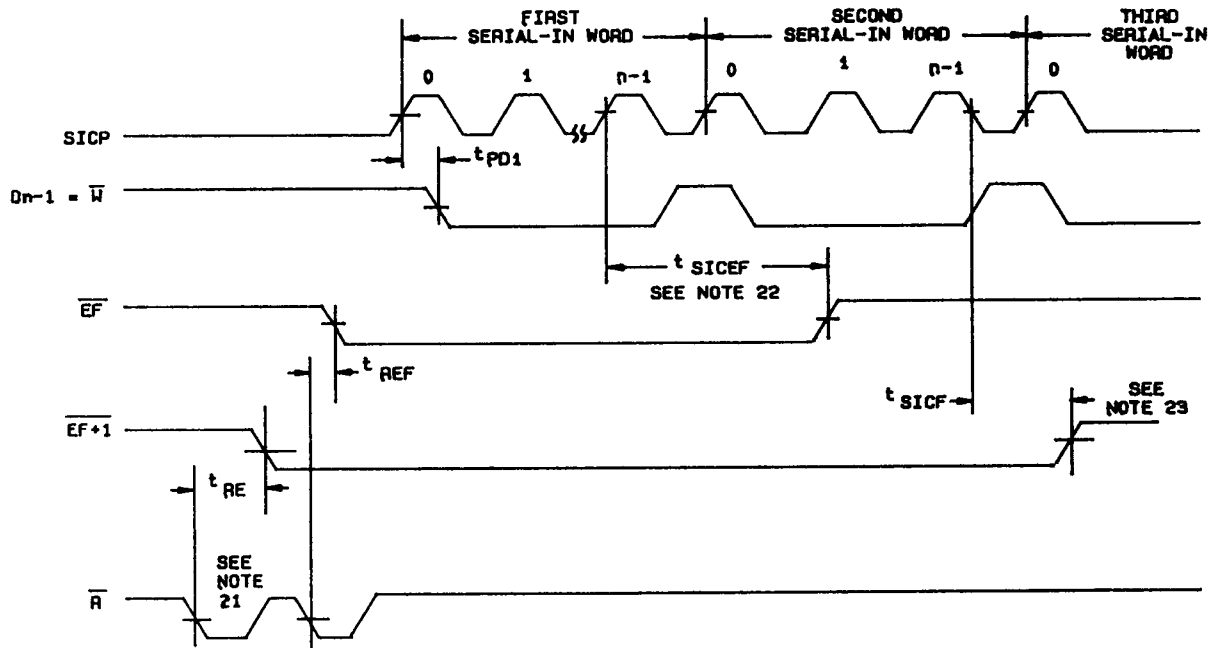


FIGURE 4. Timing waveforms - Continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 35

NOTES:

1. $\overline{EF}$, $\overline{FF}$ and $\overline{HF}$ may change status during reset, but flags will be valid at t_{RSC} .
2. $\overline{EF}$, $\overline{FF}$ and $\overline{HF}$, $\overline{AEF}$, $\overline{FF-1}$, and $\overline{EF+1}$ may change status during retransmit, but flags will be valid at t_{RTC} .
3. Data is valid on this edge.
4. The empty flag is asserted by $\overline{R}$ in the parallel-out mode and is specified by t_{REF} . The $\overline{EF}$ flag is deasserted by the rising edge of $\overline{W}$.
5. First rising edge of write after $\overline{EF}$ is set.
6. For the assertion time, t_{WFF} is used when data is written in the parallel mode. The $\overline{FF}$ is deasserted by the rising edge of $\overline{R}$.
7. After $\overline{SO/PO}$ has been setup, it cannot be dynamically changed; it can only be changed after a reset operation.
8. For the stand alone mode, $n > 4$ and the input bits are numbered 0 to $n-1$.
9. For the recommended interconnections, D_1 is to be directly tied to $\overline{W}$ and the t_{S4} and t_{H4} requirements will be satisfied. For users that modify $\overline{W}$ externally, t_{S4} and t_{H4} have to be met.
10. After $\overline{SI/PI}$ has been setup, it cannot be dynamically changed; it can only be changed after a reset operation.
11. The FIFO is full and a new read sequence is starting.
12. On the first rising edge of $\overline{SOCP}$, the $\overline{FF}$ is deasserted. In the serial-in mode, a new write operation can begin after t_{RFFS1} after $\overline{FF}$ goes HIGH. In the parallel-in mode, a new write operation can occur immediately after $\overline{FF}$ flag goes HIGH.
13. The $\overline{FF-1}$ flag is deasserted after the first $\overline{SOCP}$ of the second serial word.
14. Parallel write shown for reference only and may also use serial input mode.
15. The empty flag is asserted in the serial-out mode by using the t_{SOCEF} parameter. This parameter is measured in the worst case from the rising edge of the $\overline{SOCP}$ used to clock data bit 0. Whenever $\overline{EF}$ goes LOW, there is only one word to be shifted out. In the parallel-in mode, the $\overline{EF}$ flag is deasserted by the rising edge of $\overline{W}$. In the serial-in mode, the $\overline{EF}$ flag is deasserted by the rising edge of $\overline{W}$.
16. First write rising edge after $\overline{EF}$ is set.
17. $\overline{SOCP}$ should not be clocked until $\overline{EF}$ goes HIGH.
18. The full flag is asserted in the serial-in mode by using the t_{SICFF} parameter. This parameter is measured in the worst case from the rising edge of $\overline{SICP}$ followed by a $(t_{PD1} + t_{WFF})$ delay from the first rising edge of $\overline{SICP}$ of the last word.
19. First read rising edge after $\overline{FF}$ is set.
20. $\overline{SICP}$ should not be clocked until $\overline{FF}$ goes HIGH.
21. Parallel read shown for reference only and may also use serial output mode.
22. The empty flag is deasserted after the $N-1$ rising edge of $\overline{SICP}$ of the first serial-in word. In the serial-out mode, a new read operation can begin t_{REFSO} after $\overline{EF}$ goes HIGH. In the parallel-out mode, a new read operation can occur immediately after $\overline{FF}$ goes HIGH.
23. The $\overline{EF+1}$ flag is deasserted after the $N-1$ rising edge of $\overline{SICP}$ of the second serial-in word.

FIGURE 4. Timing waveforms - Continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 36

3.8 Notification of change. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.9 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition C or D using the circuit submitted with the certificate of compliance (see 3.6 herein).

(2) $T_A = +125^{\circ}\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroup 4 (C_{IN} and C_{OUT} measurements) shall be measured only for the initial test and after process or design changes which may affect capacitance. Sample size is 15 devices with no failures, and all input and output terminals tested.

d. Subgroups 7 and 8 tests shall include verification of the truth table.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883:

(1) Test condition C or D using the circuit submitted with the certificate of compliance (see 3.6 herein).

(2) $T_A = +125^{\circ}\text{C}$, minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 37

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*,2,3,7*,8A, 8B,9,10,11
Group A test requirements (method 5005)	1,2,3,4**,7,8A, 8B,9,10,11
Groups C and D end-point electrical parameters (method 5005)	2,3,7,8A,8B

* PDA applies to subgroups 1 and 7.

** See 4.3.1c

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).

6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.

6.5 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-5377.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89942
		REVISION LEVEL A	SHEET 38